

# CALL FOR PAPERS



## *If wire processing is right up your alley* **WAI WANTS TO HARNESS YOUR EXPERTISE** *for Wire Expo 2010*



CONVENTION & EXHIBITION:

# MAY 12-13 2010

MILWAUKEE, WISCONSIN, USA  
MIDWEST AIRLINES CENTER



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### **CALLING ALL EXPERTS**

Do you crimp, solder, or form wire? Do you mark, treat, test, assemble, package, or analyze it? Whatever your wire or cable discipline is, WAI wants your article ideas as it develops the technical program for Wire Expo in Milwaukee, Wisconsin, USA, May 12-13, 2010. Qualified experts in these areas and the topics listed below are invited to submit an article abstract. Accepted papers will be scheduled for presentation at Wire Expo and will be automatically considered for publication in *Wire Journal International* after the conference.

WAI welcomes articles in the electrical, ferrous, nonferrous, and general sectors. And because Wire Expo will co-locate with The National Electrical Wire Processing Technology Expo, special focus will be on submissions defined by the electrical processing technology topics that you know so well.

### **DESIRABLE TOPICS INCLUDE:**

- Application of non-traditional metals
- Approval agencies
- Environmental regulations
- Failure analysis
- "Green" processes
- Laser marking
- Quality (statistics and testing)
- Surface treatment and powder coating
- Terminal technology
- Workplace safety

Submit a 50-word abstract online at <http://www.wirenet.org/technical/submit.htm> or contact Marc Murray at [mmurray@wirenet.org](mailto:mmurray@wirenet.org) or Tel.: 203-453-2777, ext. 121 for more details.



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